

CHIP KOREA 2010

Date: Oct. 22, 2010

Venue: 402, Conference Room, COEX, Seoul, Korea

Type: Seminar & Table-top demo

www.it-conference.net

Organizer



Manager



Event Outline

Date	Oct. 22, 2010
Venue	402, Conference Room, COEX, Seoul, Korea
Organizer	
Manager	
Media sponsors	   
Number of attendees	120 expected
Type	Presentation & Table-top demo
Coverage	EDA, IP, foundry, packaging, test and fabless semiconductor designs

Other Events



LED Korea 2009



LED TV 2009



ISTIF 2009



LED Korea 2008



EMI/ESD Protection Seminar 2008



WPAN Technology Outlook for 2008



LED Korea 2007



Mobile Video Summit 2007



WPAN Technology Outlook for 2007



Mobile Video Summit 2006



Mobile Display & Power Management Seminar 2006



FPD for Korea 2005

Benefits

- One speaking opportunity
- Logo placement on all collaterals (banners, e-newsletters & hand-outs)
- Company profile in hand-outs
- Ad on hand-outs
- Free attendee badges
- E-mail blast (company profile)
- One media interview

* Sponsorship fee can be negotiated.

Procedures

Item	Date	Note
Abstract submission (for free presentation)	Sep. 10	
Sponsorship confirmation	Sep. 15	Via e-mail
Invoicing	Sep. 17	For sponsors
Follow-up (Confirmation form submission)	Sep. 30	<ul style="list-style-type: none">- Speech title & abstracts (100 words)- Speaker's bio (100 words) & photo- Company logo (AI, EPS or PDF)- Company overview
Ad copy /technical article (for proceedings) submission	Oct. 15	<ul style="list-style-type: none">- Type: AI, EPS or PDF (300 DPI)- Size: A4 (210mm x 297mm)
Presentation file submission	Oct. 22	Type: PowerPoint

Thank you

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